

07-01-2002



102139658

Docket No.: SOEI/0053

U.S. DEPARTMENT OF COMMERCE
Patent and Trademark Office

C15 Rec'd PGT/PTO 25 APR 2002

Tab settings

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Yuji Maeda
14-3, Shinizumi
Narita-shi, Chiba 286-8516 Japan

4-25-02

2. Name and address of receiving party(ies):

Name: Applied Materials, Inc.

Internal Address: _____

Street Address: 3050 Bowers Avenue

City: Santa Clara State: CA ZIP: 95054

Additional name(s) & address(es) attached? ☐ Yes ☒ No

Additional names(s) of conveying party(ies) ☒ Yes ☐ No

3. Nature of conveyance:

- ☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other _____

Execution Date: April 15, 2002

4. Application number(s) or registration numbers(s):

If this document is being filed together with a new application, the execution date of the application is: April 25, 2002

A. Patent Application No.(s)

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: William B. Patterson

Internal Address: Moser, Patterson & Sheridan, LLP

Street Address: 3040 Post Oak Blvd.

Suite 1500

City: Houston State: TX ZIP: 77056

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41):.....\$ 40.00

- ☐ Enclosed - Any excess or insufficiency should be credited or debited to deposit account
☒ Authorized to be charged to deposit account

8. Deposit account number:

20-0782/SOEI/0053/WBP

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Keith M. Tackett

Name of Person Signing

Keith M. Tackett
Signature

25 April 2002

Date

Total number of pages including cover sheet, attachments, and document: 3

PATENT
REEL: 13034 FRAME: 0463

ATTACHMENT TO RECORDATION COVER SHEET

Names of conveying parties (cont'd):

Koji Nakanishi
14-3 Shinizumi
Narita-shi, Chiba 286-8516 Japan

Nobuo Tokai
14-3 Shinizumi
Narita-shi, Chiba 286-8516 Japan

Ichiro Kawai
14-3 Shinizumi
Narita-shi, Chiba 286-8516 Japan

ASSIGNMENT

Whereas, I/we,

NameAddress

c/o Applied Materials Japan, Inc.,

1) **Yuji MAEDA**14-3, Shinizumi,
Narita-shi, Chiba 286-8516 Japan

c/o Applied Materials Japan, Inc.,

2) **Koji NAKANISHI**14-3, Shinizumi,
Narita-shi, Chiba 286-8516 Japan

c/o Applied Materials Japan, Inc.,

3) **Nobuo TOKAI**14-3, Shinizumi,
Narita-shi, Chiba 286-8516 Japan

c/o Applied Materials Japan, Inc.,

4) **Ichiro KAWAI**14-3, Shinizumi,
Narita-shi, Chiba 286-8516 Japan

hereinafter called assignor(s), have invented certain improvements in
SEMICONDUCTOR MANUFACTURING APPARATUS

and executed an application for Letters Patent of the United States of America therefor on even date herewith unless
 otherwise indicated below:

filed on _____, Serial No. _____; and

Whereas

APPLIED MATERIALS, INC.

3050, Bowers Avenue,

Santa Clara, CA 95054 United States of America

(assignee), desires to acquire the entire right, title and interest in the application and invention, and to any United States
 patents to be obtained therefor;

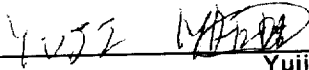
NOW THEREFORE, be it known that, for good and valuable consideration from assignee, the receipt of which is
 hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign,
 transfer, and set over unto the assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in and to
 this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States
 which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of
 Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and
 assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with
 assignee, its successors and assigns, any facts known to ME/US respecting this invention and testify in any legal
 proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or
 desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional,
 continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its
 successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being
 understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and
 assigns.

INVENTORSDATE SIGNED

1):

Name:



Yuji MAEDA

April 15, 2002

2):

Name:

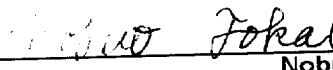


Koji NAKANISHI

April 15, 2002

3):

Name:

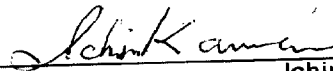


Nobuo TOKAI

April 15, 2002

4):

Name:



Ichiro KAWAI

April 15, 2002

(Legalization not required for recording but is prima facie evidence of execution under 35 U.S.C. § 261)